

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10586675
<b>Filing Date:</b>	20-Jul-2006
<b>Title of Invention:</b>	Silicon Compounds for Producing Sio2-Containing Insulating Layers on Chips
<b>First Named Inventor/Applicant Name:</b>	Ekkehard Mueh
<b>Filer:</b>	Marvin Jay Spivak/Ashenafi Chali
<b>Attorney Docket Number:</b>	288839US0PCT

Filed as Large Entity

### U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180